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FIG 1

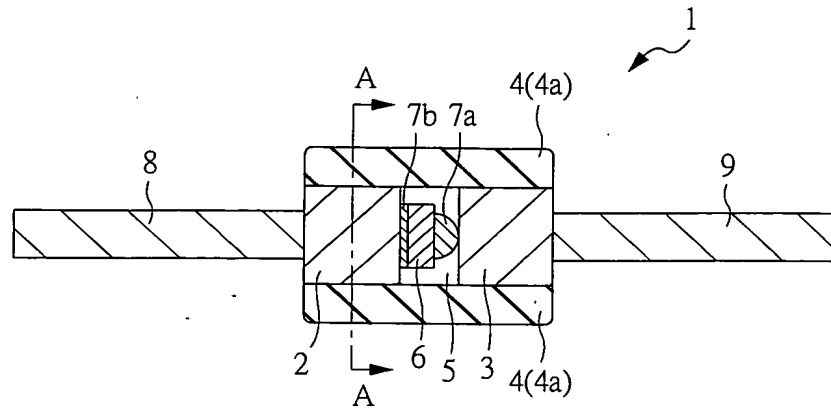


FIG 2

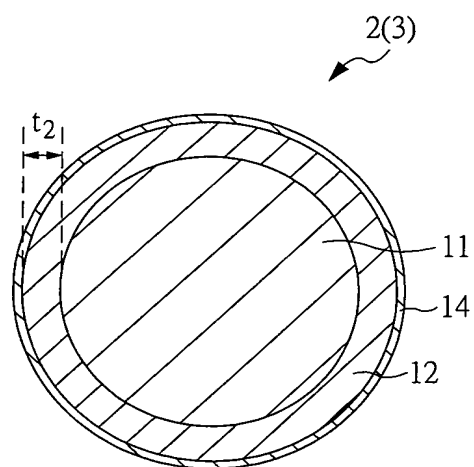


FIG 3

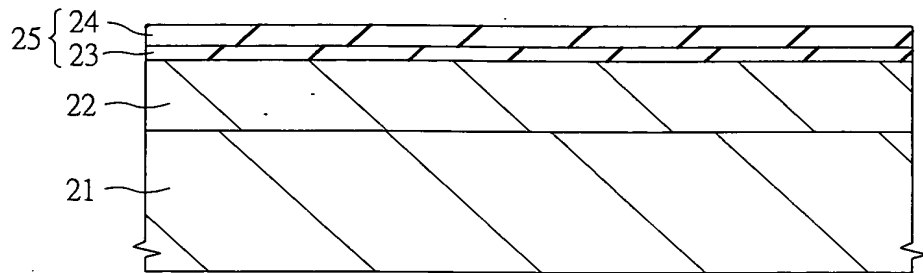


FIG 4

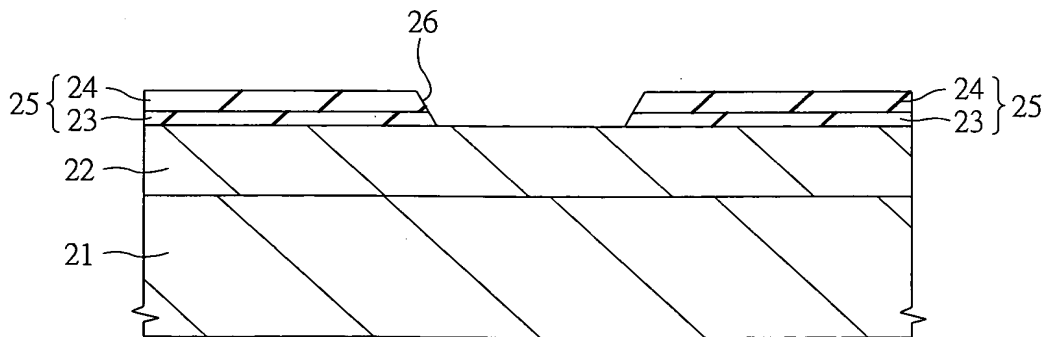


FIG 5

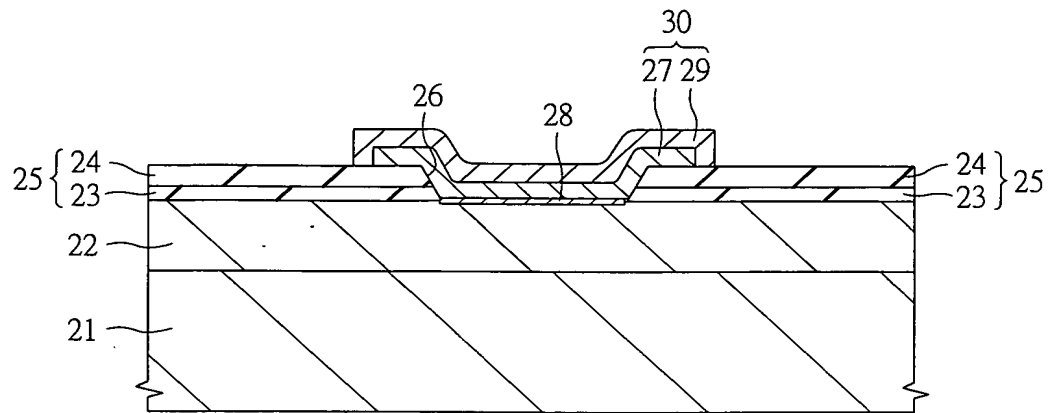


FIG 6

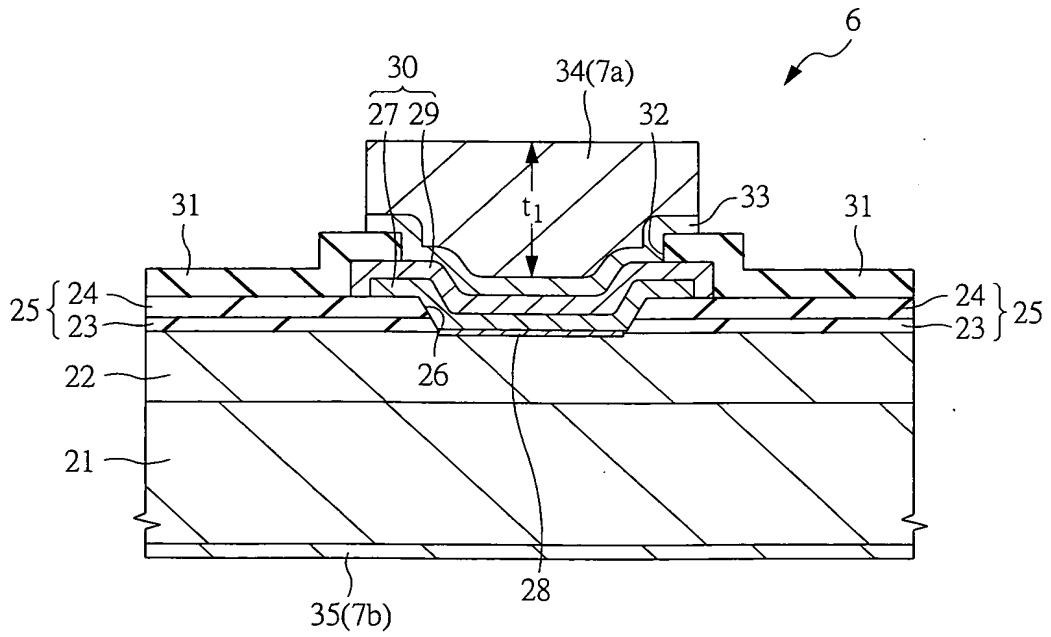


FIG 7

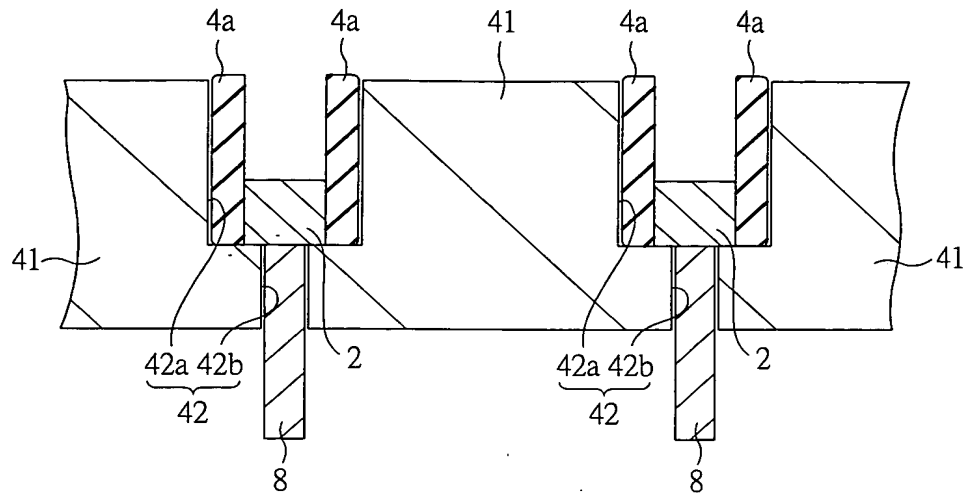


FIG 8

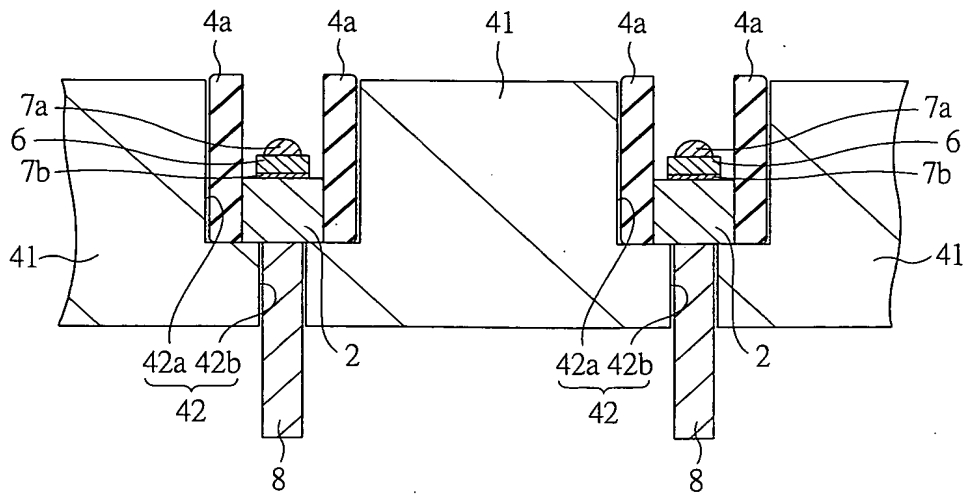


FIG 9

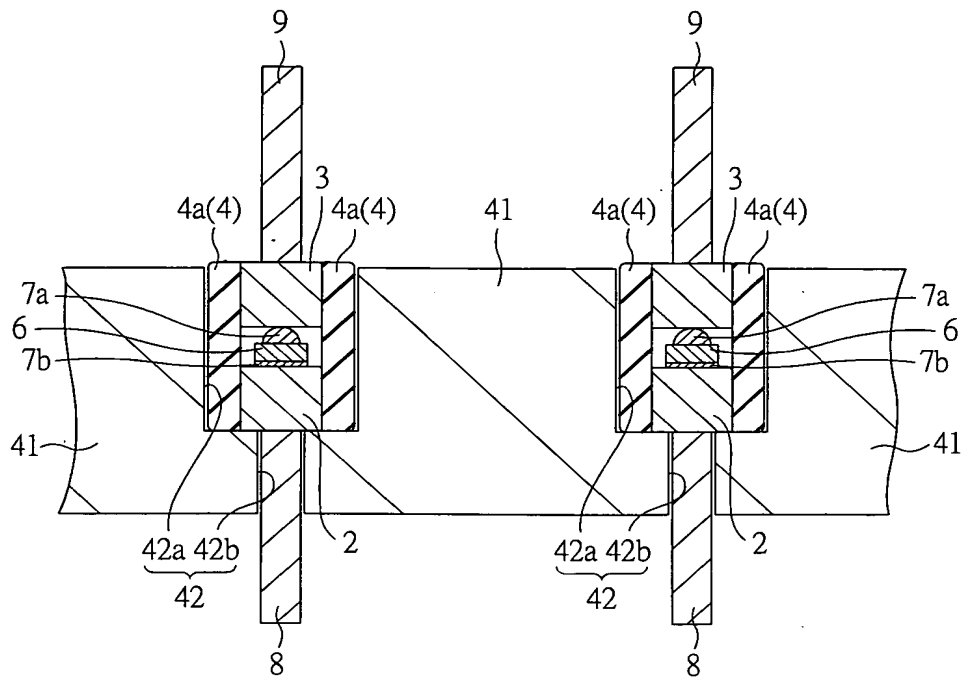


FIG 10

Characteristics			Glass material G ₁	Glass material G ₂ (low-melting-point glass)
Coefficient of thermal expansion	30~380°C	$\times 10^{-7}/K$	91	88
Concentration		$\times 10^3 kg/m^3$	4.31	4.47
Distortion point		°C	390	395
Slow cooling point		°C	430	430
Softening point		°C	575	552
Adhesive sealing temperature		°C	655	620
Working temperature		°C	820	760
Volume resistivity (log ρ)	150°C	$\Omega \cdot cm$	14.8	14.5
	250°C	$\Omega \cdot cm$	11.7	11.5
Dielectric constant	1MHz, 25°C		9.5	9.9
tan δ	1MHz, 25°C	$\times 10^{-4}$	8	7
Tone			Transparence	Transparence
Composition			K ₂ O·PbO·SiO ₂	K ₂ O·PbO·SiO ₂
Na ₂ O content		wt. %	<0.1	<0.1

FIG 11

	Dumet electrodes 2 and 3	Dumet electrode D _{ce} of comparative example
Ratio of copper layer 12 (wt%)	20~25	14~19
Ni content in core portion 11 (wt%)	41~43	46~48

FIG 12

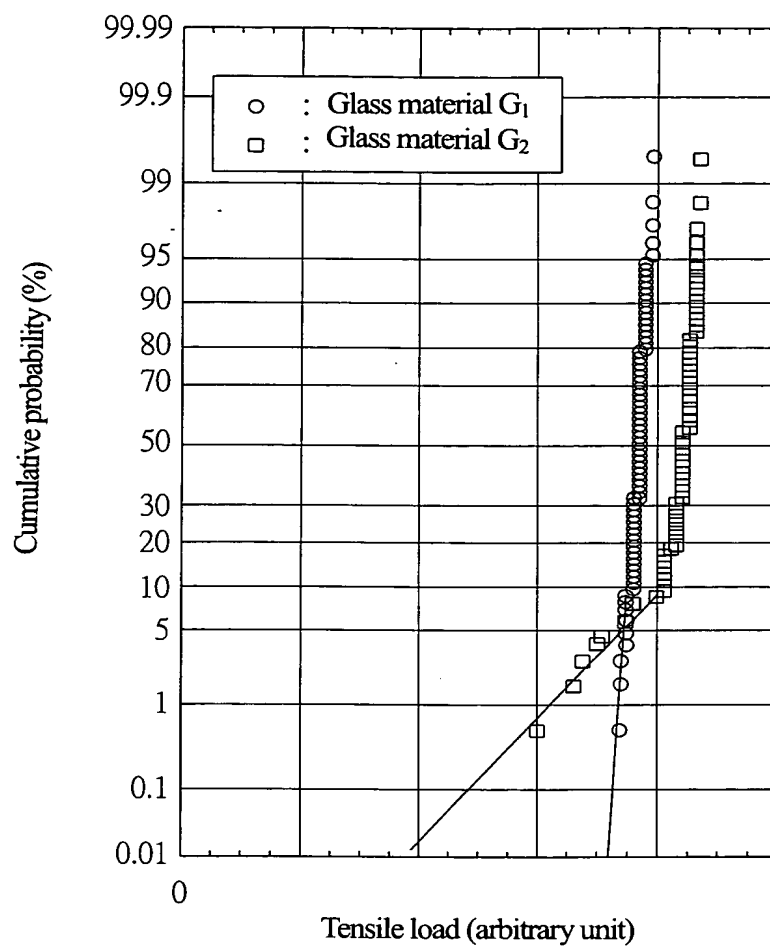


FIG 13

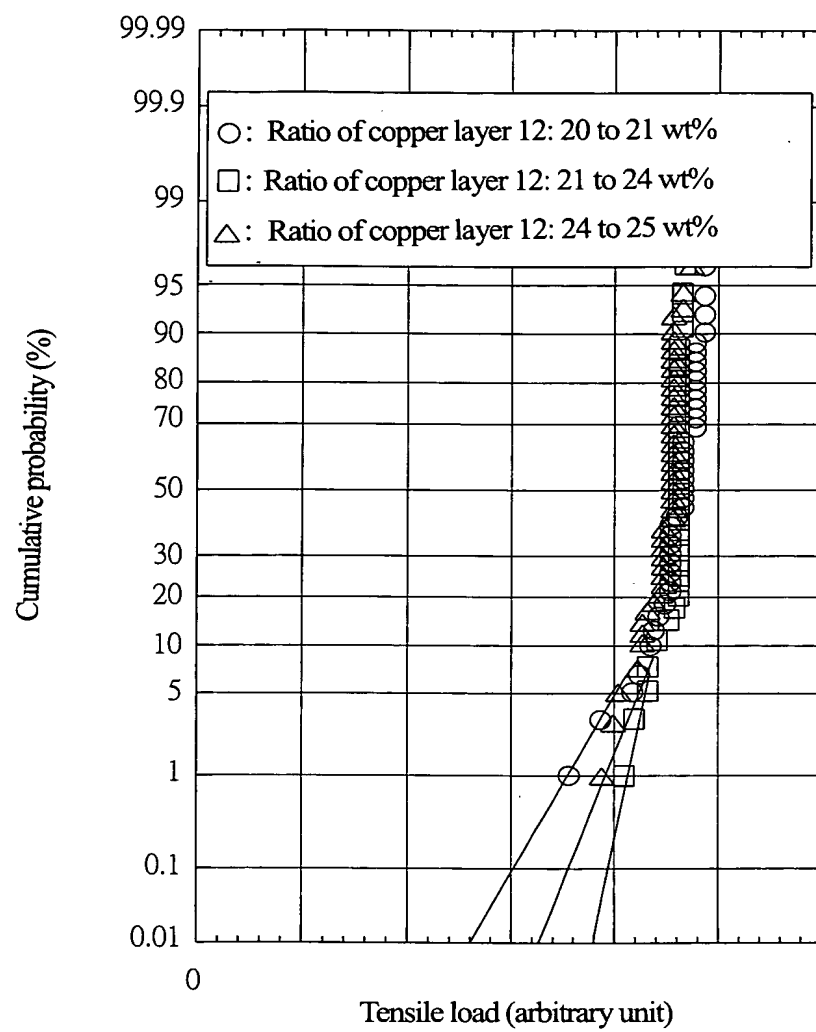


FIG 14

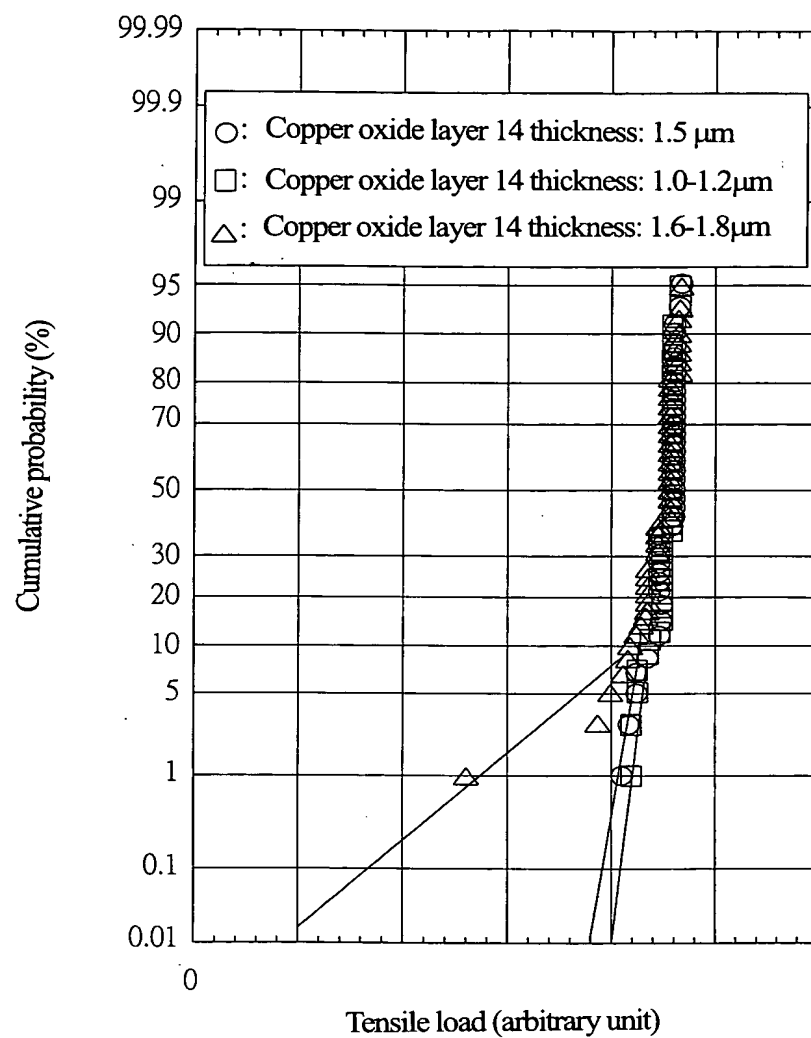


FIG 15

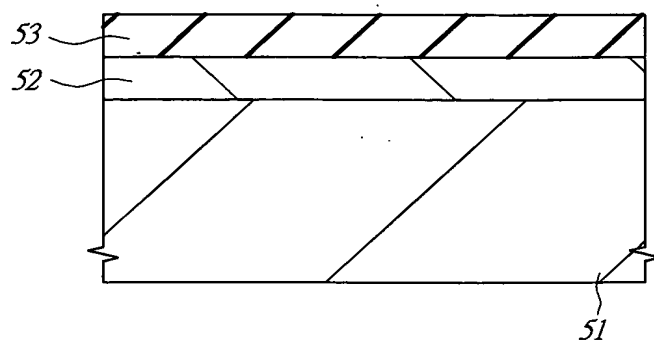


FIG 16

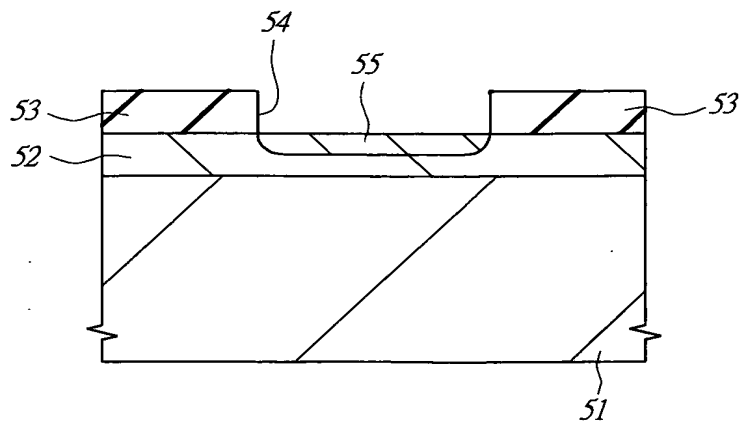


FIG 17

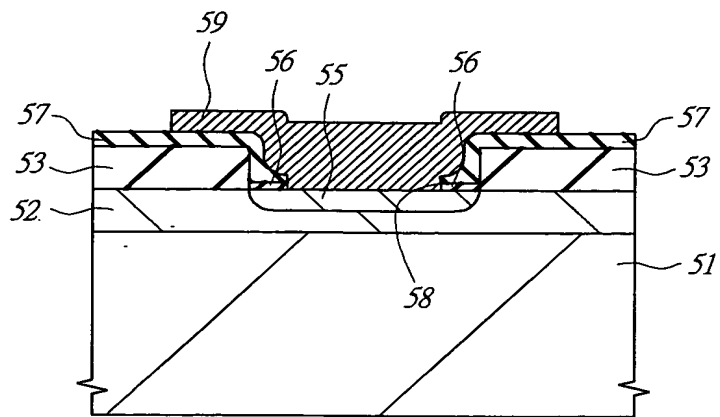


FIG. 18

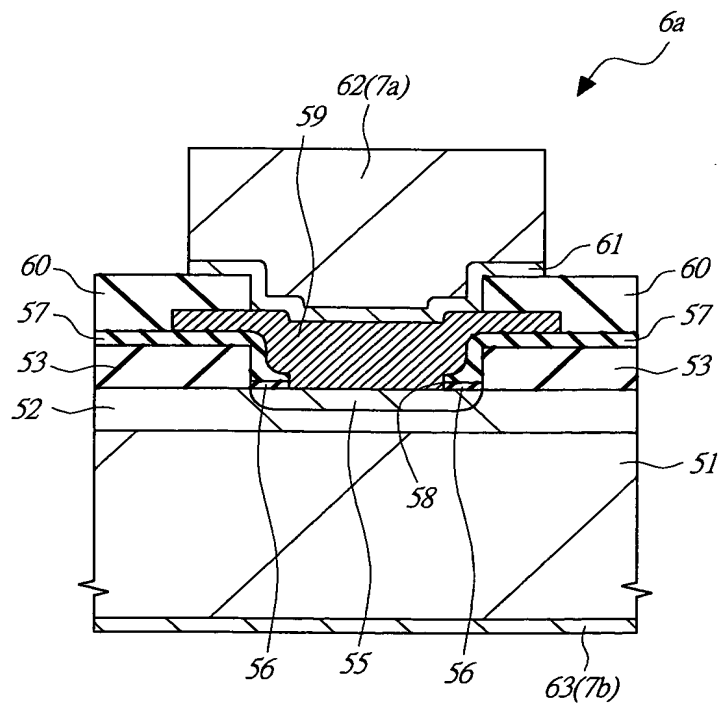


FIG 19

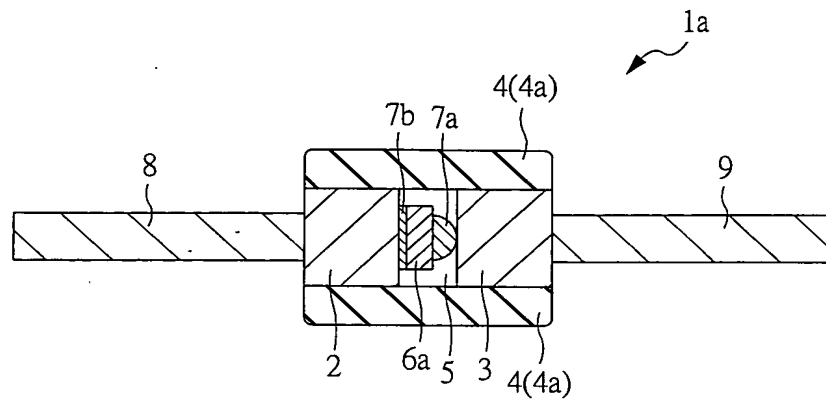


FIG 20

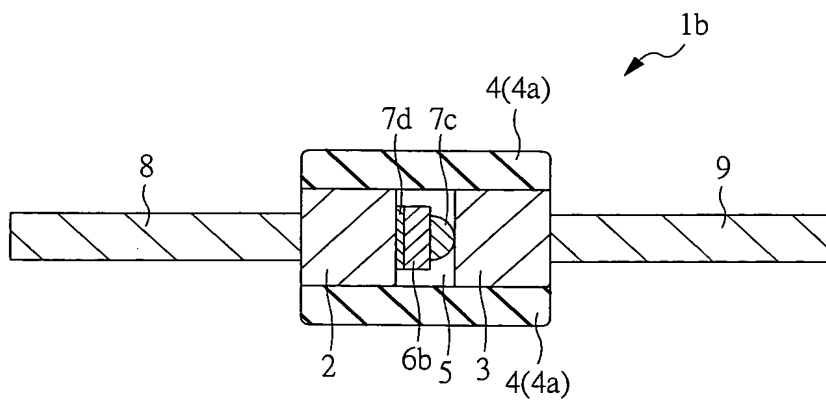


FIG 21

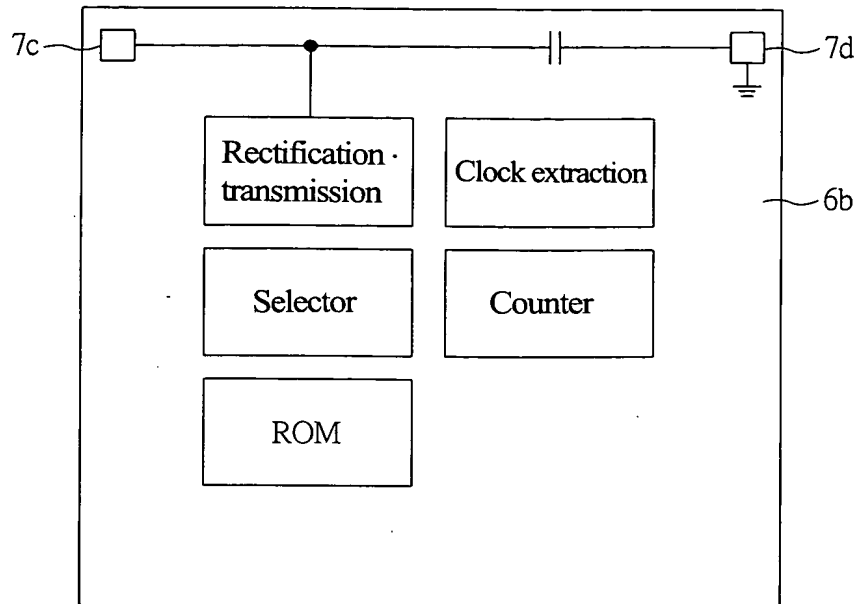


FIG 22

